

**In The Claims:**

**Claims 1-4 (canceled)**

**Claim 5. (original)** A flip-chip packaging process, comprising at least the steps of:

providing a chip and a substrate, wherein the chip has an active surface with bonding pads disposed thereon, and the substrate has a carrying surface with bump pads disposed thereon, wherein locations of the bump pads correspond to locations of the bonding pads;

disposing a plurality of supporters at a periphery of the active surface, and forming an uncured electrically conductive adhesive bump on each bump pad;

situating the chip over the carrying surface to contact the carrying surface via the supporters;

pressing the chip toward the substrate to decrease the distance between the active surface and the carrying surface, so as to cause elastic strain in the supporters and increase a contact area between each pair of electrically conductive adhesive bump and bonding pad;

stopping pressing the chip; and

curing the electrically conductive adhesive bumps.

**Claim 6. (original)** The flip-chip packaging process of claim 5, wherein disposing the supporters comprises disposing a plurality of gold bumps.

**Claim 7. (original)** The flip-chip packaging process of claim 6, wherein disposing the gold bumps comprises:

forming the gold bumps from a plurality of gold wires with a wire bonding method; and

pulling the gold wires apart from the gold bumps.

**Claim 8. (original)** The flip-chip packaging process of claim 5, wherein each electrically conductive adhesive bump comprises a polymeric material doped with a plurality of electrically conductive particles.

**Claim 9. (original)** The flip-chip packaging process of claim 8, wherein the electrically conductive particles comprise silver (Ag).

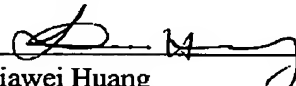
**Claim 10. (original)** The flip-chip packaging process of claim 5, wherein the electrically conductive adhesive bumps are formed on the bump pads with a screen printing method.

No new matter has been added to the application by the amendments made to the claims.

Dated: 1/25/2005

**Correspondence Address:**  
4 Venture, Suite 250  
Irvine, CA. 92618  
Tel.: (949) 660-0761

Respectfully submitted,  
J.C. PATENTS

By:   
Jiawei Huang  
Registration No. 43,330